

**METHOD AND APPARATUS FOR JOINING ADHESIVE TAPE TO BACK FACE OF
SEMICONDUCTOR WAFER**

ABSTRACT OF THE DISCLOSURE

In a method for joining an adhesive tape to a back face of a semiconductor wafer after a process of working the back face of the semiconductor wafer, the semiconductor wafer is held at a state where a face
5 having a pattern formed thereon is directed upward, and the adhesive tape is joined to the back face of the semiconductor wafer from below.

(Fig. 2)